

MLCAD 2026: Call for Papers



ACM/IEEE International Symposium on Machine Learning for CAD

September 7-9, 2026 | Parnas Hotel Jeju, Jeju Island, South Korea

Symposium Overview

The MLCAD Symposium is dedicated to the applications of Machine Learning (ML) and Artificial Intelligence (AI) across all aspects of CAD and electronic system design. Sponsored by the ACM Special Interest Group on Design Automation (SIGDA) and the IEEE Council on Electronic Design Automation (CEDA), MLCAD 2026 will be held in person on Jeju Island, South Korea. The event begins with a welcome reception on the evening of September 7, 2026. We invite papers covering any aspect of applying ML/AI to enhance the CAD of electronic chips and systems. Topics of interest include, but are not limited to, algorithms, tools, example applications, benchmarks, datasets, and innovative solutions - such as using Large Language Models (LLMs) as agents for optimization, algorithm discovery, and automation.

Paper Submission:

May 16, 2026 (AOE)

May 23, 2026 (AOE)

Notification: July 7, 2026

Camera Ready Version:

July 25, 2026

Website:

<https://mlcad.org/>

Paper Submission (Research Track)

Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, using the ACM format). References and appendices are excluded from the page limit. To facilitate a double-blind review process, submissions must be anonymous. Papers must describe original work that has not been published, accepted, or is currently under review elsewhere. Accepted papers will be invited to submit an extended version in a special issue of ACM Transactions on Design Automation of Electronic Systems (TODAES). Submission website: <https://easychair.org/conferences/?conf=mlcad2026>

Symposium Proceedings

Formal shared ACM/IEEE proceedings containing all accepted papers will be published. These papers will be available in both the IEEE Xplore Digital Library and the ACM Digital Library.

ACM policies

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